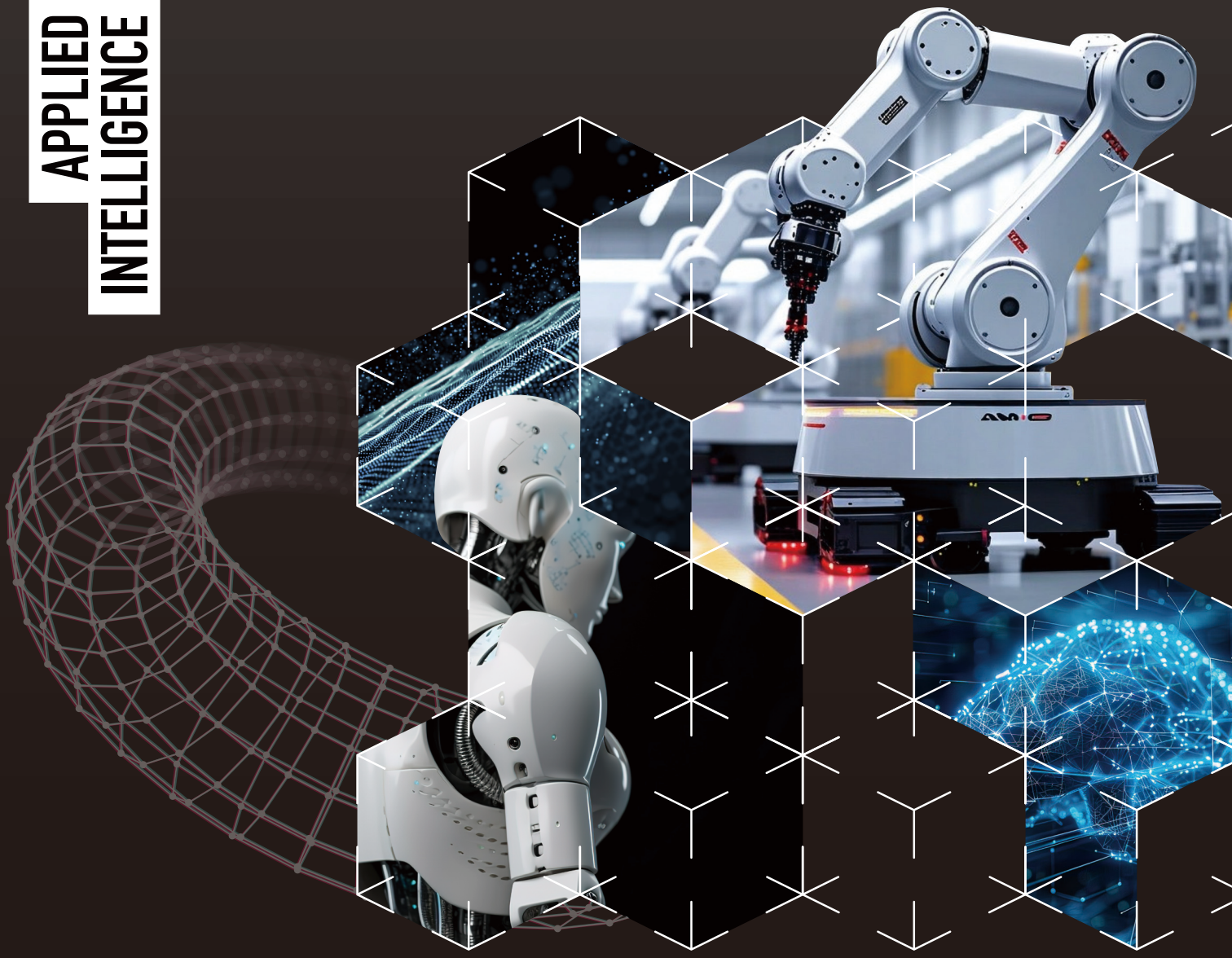
innodisk

APPLIED INTELLIGENCE



INNODISK APEX SERIES
EDGE AI SYSTEMS

Powered by NVIDIA | Qualcomm | Intel

EMPOWERING ENTERPRISE & INDUSTRY EDGE INTELLIGENCE

From the cloud to the edge, AI is evolving. As data grows and decisions move closer to where actions happen, the future of intelligence is no longer centralized—it's distributed, responsive, and real-time.

Cloud AI: Facing Bottlenecks

AI first proved its potential in the cloud, delivering unprecedented computing power and scalability. However, as industries accelerate toward real-world adoption—seeking smarter, faster, and more efficient solutions—new challenges and roadblocks emerge.

Data privacy & security concerns

Latency & cost pressures

Limited flexibility for customization

Edge AI: The Practical Answer

Edge AI brings intelligence closer to where data is generated—scaling down large models to run efficiently at endpoints. It delivers key advantages that overcome the limitations of cloud-based AI, making intelligence more practical, efficient, and widely accessible.
Now, the era of Enterprise Edge AI and Industrial Edge AI has truly arrived.

Data security

Reduced cost

Lower latency

Customized intelligence

Customized AI Solutions & One-Stop Integration

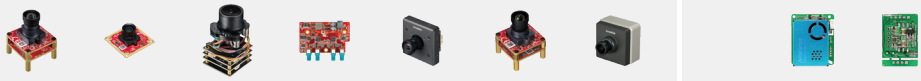
Building on the shift from the cloud to the edge, Innodisk delivers comprehensive edge AI systems and flexible product design services—leveraging years of expertise and intelligent building blocks to provide scalable, industrial-grade, and fully compatible solutions.

20 YEARS+ Specialized Industrial Experience

200+ Dedicated In-House R&D Engineers

- Thermal Engineer
- ID Designer/ ME
- Electronic Engineer
- Software Developer (BIOS, FW, OS image, Driver, AP)
- Component Engineer
- System Architect (x86/ARM)
- DQA Engineer
- Project Manager
- EMI/Safety Regulatory Engineer

Innodisk AI Building Blocks

CLOUD MANAGEMENT	Cloud AI	iCAP (Innodisk Cloud Administration Platform)
SOFTWARE / FIRMWARE	iSeries Software	iSMART / iTracker / iOPAL / iRAID
	Innodisk AI SDK	AccelTune / AccelBrain / iVIT
EDGE AI SYSTEM	AI Accelerator	NVIDIA Qualcomm Intel
	APEX Series	
KEY COMPONENT AND PERIPHERAL	Flash / DRAM / Display / Networking / Storage / Wi-Fi	
SENSOR	Camera / Air Sensor	

INNOVATING WITH THE WORLD'S LEADING EDGE AI CORES

NVIDIA

The RTX Series AI accelerators deliver high-performance graphics, longevity, and versatile AI computing.

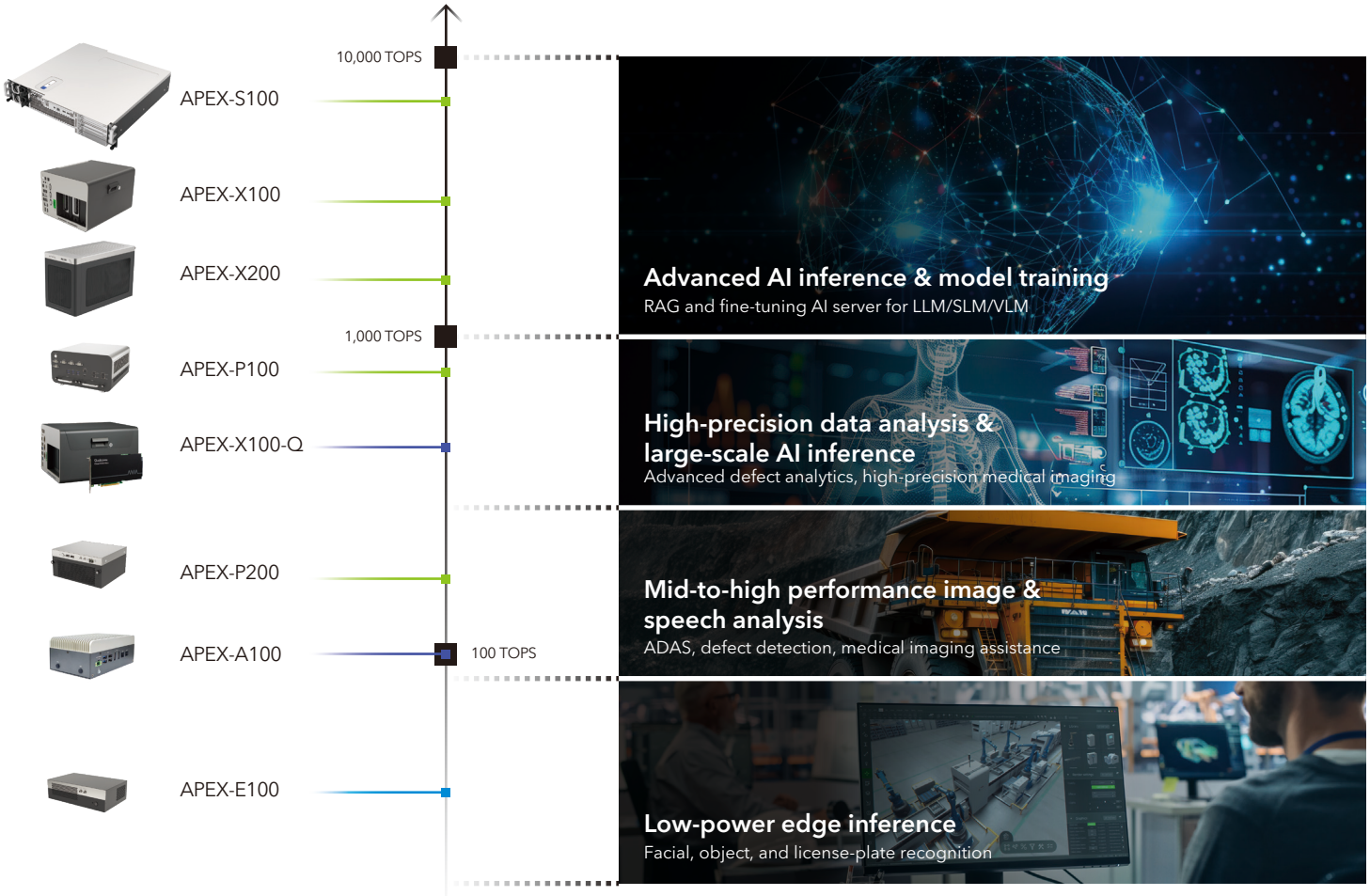
Qualcomm

Cloud AI 100 Ultra accelerator for on premise LLMs;
Dragonwing IQ Series for scalable edge AI.

Intel

Core Ultra processors with built-in NPUs deliver essential AI computing power;
Intel x86 platform offers compatibility for various use cases.

INNODISK EDGE AI SOLUTION LANDSCAPE



(TOPS @ INT8)

NVIDIA

Model Name	APEX-S100	APEX-X100
Product Highlight	MGX AI modular server supporting NVIDIA data center accelerators for high-end AI model training	Supports NVIDIA professional-grade accelerators for lightweight AI training and complex inference
AI Accelerator	- NVIDIA L40S - RTX PRO 6000 Blackwell Server Edition - Tesla H200 NVL Up to dual accelerator (varies by SKU)	- NVIDIA RTX PRO 6000 Blackwell Max-Q / 96GB GDDR7 - 24,064 Cuda Cores - 752 Tensor Cores - 188 RT Cores - NVIDIA RTX 6000 Ada / 48GB GDDR6 (Optional)
CPU	- Intel Xeon 6731P - Intel Xeon 6730P - Intel Xeon 6736P	- Intel Core i9-13900E - Intel Core i7-13700E - Intel Core i9-14900
Memory	Support up to DDR5 1TB (Up to 768GB pre-installed) (varies by SKU)	Support up to DDR5 192GB (64GB / 128GB / 192GB pre-installed)
Storage	Up to 2 × 2TB M.2 + 4 × 3.84TB E1.S pre-installed	512GB / 1TB / 2TB pre-installed
Display	1 × Mini DP	1 × HDMI, 2 × DP++, *VGA
Ethernet	2 × 10Gbps or 2 × 25Gbps or 2 × 200Gbps (varies by SKU)	- 1 × 10Gbps - 3 × 2.5Gbps (30W PoE × 2)
Expansion Slots	- 2 × M.2 2280 / 22110 M Key - 4 × E1.S - 2 × PCIe ×16 (Gen 5 ×16)* - 1 × PCIe ×16 (Gen 5 ×16) - 1 × PCIe ×8 (Gen 5 ×16)	- 1 × M.2 3052 B Key - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key - 2 × PCIe ×16 (Gen 4 ×16)* - 1 × PCIe ×16 (Gen 3 ×4) - 1 × PCIe ×4 (Gen 3 ×4) - 1 × PCIe ×1 (Gen 3 ×1)
External I/O	2 × USB 2.0	- 3 × COM - 1 × USB 3.2 Gen 2 ×2 (Type-C) - 8 × USB 3.2 Gen 2 ×1 - 1 × 8 bit GPIO
Features	Hot-swappable E1.S SSD & CRPS PSU	Out-of-band (OOB)
Power Input/Consumption	AC 220V	DC 24V (24V@19.8A)
Dimension (L x W x H/mm)	438 × 420 × 88	340 × 279 × 215
Operating Temperature	0°C ~ 30°C	0°C ~ 50°C

		TAIWAN EXCELLENCE 2026
APEX-X200	APEX-P100	APEX-P200
Flexible and compact system design supporting a wide range of NVIDIA accelerators	Compact design supports MXM Type-B accelerators for lightweight AI inference	Ultra-compact 182 × 158.6 mm design supports MXM Type-A accelerators and operates from -20°C ~ 60°C
- NVIDIA RTX 5080 / 16GB GDDR7 - 10,752 CUDA Cores - 336 Tensor Cores - 84 RT Cores	- NVIDIA RTX 5000 Ada /16GB GDDR6 - 9,728 Cuda Cores - 304 Tensor Cores - 76 RT Cores	- NVIDIA RTX 2000 Ada / 8GB GDDR6 - 3,072 Cuda Cores - 96 Tensor Cores - 24 RT Cores - NVIDIA RTX PRO 2000 Blackwell planning
Intel Core Ultra 7 265	Intel Core i7-13700E	Intel Core i7-13800HE
Support up to DDR5 96GB (64GB pre-installed)	Support up to DDR5 64GB (32GB pre-installed)	Support up to DDR5 64GB (32GB pre-installed)
512GB pre-installed	512GB pre-installed	512GB pre-installed
1 × DP 2.1, 1 × HDMI 2.1	5 × DP++	1 × HDMI
2 × 2.5Gbps	5 × 2.5Gbps	3 × 2.5Gbps (30W PoE × 2)
- 2 × M.2 2280 M key - 1 × M.2 2230 E key - 2 × PCIe ×16 (Gen 5 x16)*	- 2 × M.2 2280 M Key - 1 × MXM Type B/B+ (Gen 4 ×16)	- 1 × M.2 2280 M Key - 1 × M.2 2230 E Key - 1 × MXM Type A (Gen 4 ×8)
- 4 x COM - 8 × USB 3.2 Gen 2 ×1 - 2 × USB 2.0	- 4 × COM - 1 × USB 3.2 Gen 2 ×2 (Type-C) - 6 × USB 3.2 Gen 2 ×1 - 2 × USB 2.0 - 1 × 7 bit GPIO	- 2 × COM - 2 × USB 3.2 Gen 2 ×1 - 2 × USB 2.0
Out-of-band (OOB)	Out-of-band (OOB)	Out-of-band (OOB)
FLEX ATX 850W PSU	DC 24V (24V@19.8A)	DC 19V (19V@10.5A)
381 x 185 x 235	280 × 270 × 148.2	182 × 158.6 × 90
0°C ~ 45°C	0°C ~ 50°C	-20°C ~ 60°C

Qualcomm

Intel

APEX-X100-Q	APEX-A100	APEX-E100
Supports Qualcomm AI 100 Ultra accelerator, ideal for LLM and SLM workloads	Featuring Qualcomm Dragonwing industrial-grade SoC for edge AI applications	Powered by Intel's latest design with built-in NPU for lightweight AI applications
- Qualcomm Cloud AI 100 Ultra - 870 TOPS (INT8) - 288 TFLOPS (FP16)	- 2 × Hexagon Tensor Processor NPU - 100 TOPS Dense (INT8) - 200 TOPS Sparse (INT8)	- Intel AI Boost via CPU + GPU + NPU - Up to 36 TOPS (INT8)
Intel Core i7-13700E	Qualcomm Dragonwing IQ-9075	- Intel Core Ultra 7 165H - Intel Core Ultra 5 135H - Intel Core Ultra 3 105U
Support up to DDR5 192GB (192GB pre-installed)	36GB LPDDR5X (on board)	Support up to DDR5 96GB (16GB pre-installed)
2TB pre-installed	128GB UFS pre-installed	512GB pre-installed
1 × HDMI, 2 × DP++, *VGA	2 × DP1.2, 1 × eDP	2 × HDMI
1 × 10Gbps 3 × 2.5Gbps (30W PoE × 2)	2 × 2.5Gbps	2 × 2.5Gbps
- 1 × M.2 3052 B Key - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key - 2 × PCIe ×16 (Gen 4 ×16) - 1 × PCIe ×16 (Gen 3 ×4) - 1 × PCIe ×4 (Gen 3 ×4) - 1 × PCIe ×1 (Gen 3 ×1)	- 1 × M.2 3052 B Key - 1 × M.2 2280 M Key - 1 × M.2 2230 E Key	- 1 × M.2 2280 M Key - 1 × M.2 2230 E Key
- 3 × COM - 1 × USB 3.2 Gen 2 ×2 - 8 × USB 3.2 Gen 2 ×1 - 1 × 8 bit GPIO	- 1 × COM - 3 × USB 3.2 Gen 2 ×1 - 1 × USB 3.2 Gen 2 ×1 (Type-C) - 2 × USB 2.0 - 1 × CAN FD	- 1 × COM - 2 × USB 3.2 Gen 2 ×1 - 2 × USB 3.2 Gen 1 ×1 - 2 × USB 2.0
Out-of-band (OOB)	2 × MIPI over FPC	2 × MIPI over Type-C
DC 24-48V (24V@14A)	DC 9-36V (12V@2.6A)	DC 12V (12V@12.5A)
340 × 279 × 215	180 × 108.7 × 69	188 × 140 × 56
0°C ~ 40°C	-40°C ~ 70°C	-20°C ~ 60°C

TAILORED DESIGN & QUALITY MANUFACTURING

Backed by proven expertise and trusted global partnerships, Innodisk delivers a flexible collaborative approach that seamlessly integrates software, hardware, and firmware ensuring solutions tailored to your unique business needs.

AI Accelerators with diverse solutions

Flexible product design and collaboration approach

Seamless integration capabilities

Expertise in vertical markets and applications

4,000+ global customer experience

Global technical and service network

Our 27,000 m² R&D and Manufacturing Center in Yilan, Taiwan, equipped with advanced technologies and strict quality control, ensures superior product quality.

ABOUT INNODISK

Founded in 2005, Innodisk is a global leader in industrial memory and storage, now advancing into edge AI. From reliable storage to intelligent edge solutions, we empower real-time data, computing, and decision-making to help architect a more intelligent world.

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